SN54AC573...J OR W PACKAGE SN74AC573...DB, DW, N, NS, OR PW PACKAGE

SCAS542D - OCTOBER 1995 - REVISED OCTOBER 2003

- 2-V to 6-V V_{CC} Operation
- Inputs Accept Voltages to 6 V
- Max t_{pd} of 9 ns at 5 V
- 3-State Outputs Drive Bus Lines Directly

description/ordering information

These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. The devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

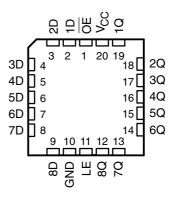
The eight latches are D-type transparent latches. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D Inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines in a bus-organized system without need for interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

		EVV)	
OE [1D [2D [3D [4D [5D [7D [8D]	1 2 3 4 5 6 7 8 9	20 19 18 17 16 15 14 13 12] V _{CC}] 1Q] 2Q] 3Q] 4Q] 5Q] 6Q] 7Q] 8Q
GND	10	11] LE

SN54AC573 . . . FK PACKAGE (TOP VIEW)



T _A	PACKAG	Et	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74AC573N	SN74AC573N
		Tube	SN74AC573DW	40570
	SOIC – DW	Tape and reel	SN74AC573DWR	AC573
–40°C to 85°C	SOP – NS	Tape and reel	SN74AC573NSR	AC573
	SSOP – DB Tape and reel		SN74AC573DBR	AC573
		Tube	SN74AC573PW	10570
	TSSOP – PW	Tape and reel	SN74AC573PWR	AC573
	CDIP – J	Tube	SNJ54AC573J	SNJ54AC573J
–55°C to 125°C	CFP – W	Tube	SNJ54AC573W	SNJ54AC573W
	LCCC – FK	Tube	SNJ54AC573FK	SNJ54AC573FK

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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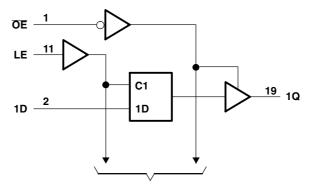
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description/ordering information (continued)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

	FUNCTION TABLE (each latch)											
	INPUTS	OUTPUT										
ŌE	LE	D	Q									
L	Н	Н	Н									
L	Н	L	L									
L	L	Х	Q ₀									
Н	Х	Х	z									

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}		–0.5 V to + 7 V
Input voltage range, V _I (see Note 1)		–0.5 V to V _{CC} + 0.5 V
Output voltage range, V _O (see Note 1)		–0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} (V _I < 0 or V _I > V _{CC})		±20 mA
Output clamp current, I_{OK} (V _O < 0 or V _O > V _{CC}	.)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$		±50 mA
Continuous current through, V _{CC} or GND		±200 mA
Package thermal impedance, θ_{JA} (see Note 2):	: DB package	70°C/W
	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
	PW package	83°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



SN54AC573, SN74AC573 **OCTAL D-TYPE TRANSPARENT LATCHES** WITH 3-STATE OUTPUTS SCAS542D - OCTOBER 1995 – REVISED OCTOBER 2003

recommended operating conditions (see Note 3)

			SN54A	C573	SN74A	C573	
			MIN	MAX	MIN MAX		UNIT
V _{CC}	Supply voltage		2	6	2	6	V
		$V_{CC} = 3 V$	2.1		2.1		
ViH	High-level input voltage	$V_{CC} = 4.5 V$	3.15		3.15		V
		V _{CC} = 5.5 V	3.85		3.85		
		$V_{CC} = 3 V$		0.9		0.9	
V _{IL}	Low-level input voltage	$V_{CC} = 4.5 V$		1,35		1.35	V
		$V_{CC} = 5.5 V$		1.65		1.65	
VI	Input voltage		0	V _{CC}	0	V_{CC}	V
Vo	Output voltage		00	V_{CC}	0	V_{CC}	V
		V _{CC} = 3 V	0	-12		-12	
l _{OH}	High-level output current	$V_{CC} = 4.5 V$	0	-24		-24	mA
		$V_{CC} = 5.5 V$		-24		-24	
		$V_{CC} = 3 V$		12		12	
l _{OL}	Low-level output current	$V_{CC} = 4.5 V$		24		24	mA
		V _{CC} = 5.5 V		24		24	
$\Delta t / \Delta v$	Input transition rise or fall rate			8		8	ns/V
T _A	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			T	_A = 25°C		SN54A	C573	SN74A	C573	
PARAMETER	TEST CONDITIONS	v _{cc}	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
		3 V	2.9			2.9		2.9		
	I _{OH} = -50 μA	4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
V _{OH}	I _{OH} = -12 mA	3 V	2.58			2.48		2.48		V
		4.5 V	3.94			3.8		3.8		
	$I_{OH} = -24 \text{ mA}$	5.5 V	4.94			4.8	j.	4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85	N.	3.85		
		3 V			0.1	4	0.1		0.1	
	I _{OL} = 50 μA	4.5 V			0.1	5	0.1		0.1	
		5.5 V			0.1	na	0.1		0.1	
V _{OL}	I _{OL} = 12 mA	3 V			0.36	PO.	0.44		0.44	V
		4.5 V			0.36	Q	0.44		0.44	
	I _{OL} = 24 mA	5.5 V			0.36		0.44		0.44	
	I _{OL} = 75 mA	5.5 V					1.65		1.65	
l _l	$V_{I} = V_{CC} \text{ or } GND$	5.5 V			±0.1		±1		±1	μA
I _{OZ}	$V_{O} = V_{CC} \text{ or } GND$	5.5 V			±0.25		±5		±2.5	μA
I _{CC}	$V_I = V_{CC} \text{ or } GND, I_O = 0$	5.5 V			4		80		40	μA
Ci	$V_I = V_{CC}$ or GND	5 V		5						pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

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timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

		T _A = 2	25°C	SN54AC573		SN74AC573		
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration, LE high	6		8	5.4	7		ns
t _{su}	Setup time, data before LE \downarrow	3.5		5	11K	4		ns
t _h	Hold time, data after LE \downarrow	2		3		2		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

		T _A = 25°C		SN54AC573		SN74AC573		
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
tw	Pulse duration, LE high	4		6	J. M	5		ns
t _{su}	Setup time, data before LE \downarrow	3		4.5	11r	3.5		ns
t _h	Hold time, data after LE \downarrow	2		3	7	2		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3 $\breve{V} \pm 0.3$ V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM		T _A = 25°C		SN54AC573		SN74AC573		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	ſ	0	2.5	13	1.5	16.5	2	15	
t _{PHL}	D	Q	2.5	12	1.5	15.5	2	14	ns
t _{PLH}		0	2.5	13	1.5	16.5	2	15	
t _{PHL}	LE	Q	2.5	12	1.5	2 15.5	2	14	ns
t _{PZH}	OE	0	2.5	11	1.5	13.5	2	12	
t _{PZL}	ÛE	Q	2.5	11	5.5	14	2	12.5	ns
t _{PHZ}	ŌĒ	Q	2.5	12.5	1.5	15	2	13.5	ns
t _{PLZ}	UE	Ŷ	2.5	9.5	1.5	12	2	10.5	115

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	T _A = 25°C		SN54AC573		SN74AC573		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	ſ	0	2.5	10	1.5	13	2	11.5	
t _{PHL}	D	Q	2.5	9.5	1.5	12.5	2	11	ns
t _{PLH}	LE	0	2.5	9.5	1.5	12.5	2	11	
t _{PHL}	LE	Q	2.5	8.5	1.5	2 11.5	2	10	ns
t _{PZH}	ŌĒ	0	2.5	9	1.5	11.5	2	10	
t _{PZL}	ÛE	Q	2.5	8.5	F .5	11	2	9.5	ns
t _{PHZ}	ŌĒ	Q	2.5	11	1.5	13.5	2	12	ns
t _{PLZ}	UE	ý	2.5	8	1.5	10.5	2	9	115

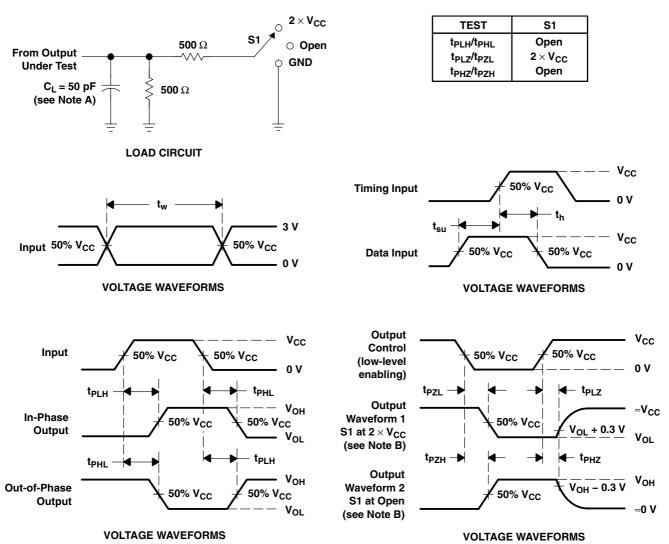
operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER		TEST CONDITIONS				
C _{pd}	Power dissipation capacitance	C _L = 50 pF,	f = 1 MHz	25	pF		

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SCAS542D - OCTOBER 1995 - REVISED OCTOBER 2003



PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_L includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.

- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_r \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



18-Sep-2008

PACKAGING INFORMATION

TEXAS TRUMENTS

www.ti.com

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AC573DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74AC573DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573N	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AC573NE4	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AC573NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74AC573PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC573PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect. NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.



(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details. TBD: The Pb-Free/Green conversion plan has not been defined.

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Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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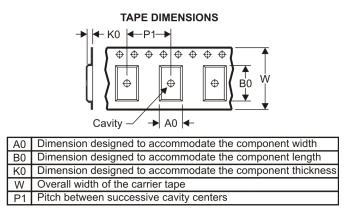
PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC573DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AC573DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74AC573NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74AC573PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

5-May-2011



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC573DBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74AC573DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74AC573NSR	SO	NS	20	2000	346.0	346.0	41.0
SN74AC573PWR	TSSOP	PW	20	2000	346.0	346.0	33.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994. β . This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



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